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IN THE UNITED STATES PATENT AND
TRADEMARK OFFICE

PATENT

Applicant(s):	Misuo Sugiyama; Hatsuyuki Arai	Docket No.:	30598.0004
Reissue of Patent No.:	5,605,499	Application No.:	08/421,706
Issued:	February 25, 1997	Filed:	April 13, 1995
Title:	FLATTENING METHOD AND FLATTENING APPARATUS OF A SEMICONDUCTOR DEVICE	Examiner:	Andrew Weinberg

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination of the captioned reissue application, please amend the application as follows:

In the Claims

Rewrite claim 1 as follows:

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1. (Amended) A flattening method of a semiconductor device by a chemical-mechanical polishing process comprising,
preparing a synthetic resin polishing cloth in a circular form and a tool for forming a surface layer of the synthetic resin polishing cloth to have fluff thereon in a polishing process, said tool having an annular shape with a diameter less than a radial length of the polishing cloth, and